

SOT354-1

plastic surface-mounted single in-line power package; 9 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SMS9P
Package type industry code	SMS9P
Package style descriptive code	SMS (surface-mounted single in-line)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		23.6	-	23.7	24	mm
E	package width		11.8	-	12	12.2	mm
A	seated height		4.2	-	4.9	4.9	mm
A ₂	package height		4.4	-	4.4	4.6	mm
n ₂	actual quantity of termination		-	-	9	-	



2. Package outline

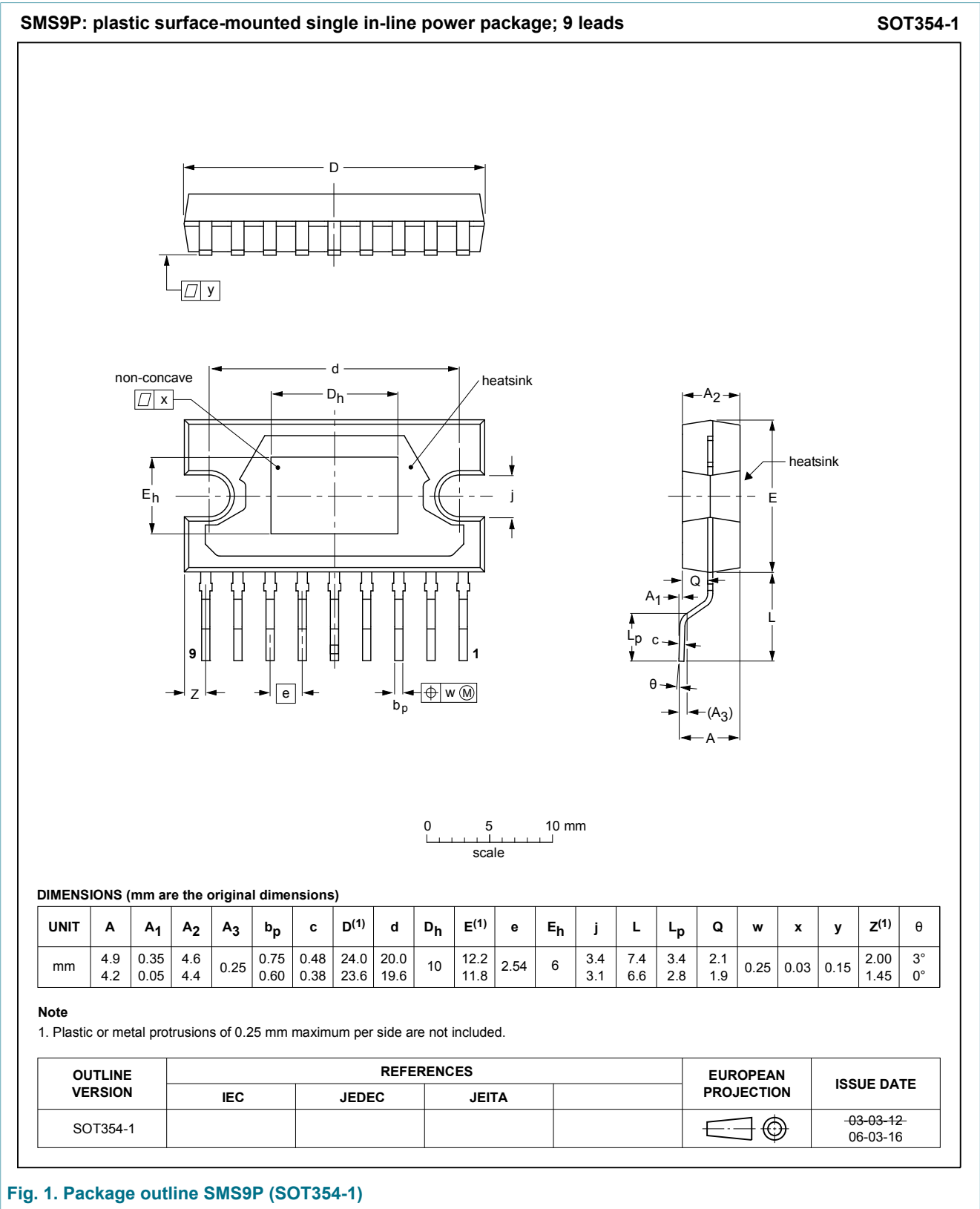


Fig. 1. Package outline SMS9P (SOT354-1)

3. Legal information

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